

Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from, Europe, America and south Asia, supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts, Customers Priority, Honest Operation, and Considerate Service", our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip, ALPS, ROHM, Xilinx, Pulse, ON, Everlight and Freescale. Main products comprise IC, Modules, Potentiometer, IC Socket, Relay, Connector. Our parts cover such applications as commercial, industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

Email & Skype: info@chipsmall.com Web: www.chipsmall.com

Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China







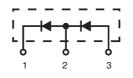


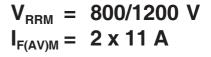
Phase-leg Rectifier Diode ISOPLUS220™

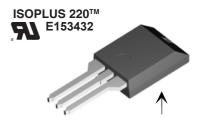
Electrically Isolated Back Surface

V _{RSM}	V _{RRM}	Туре
900	800	DSP 8-08AC
1300	1200	DSP 8-12AC

Preliminary Data Sheet







Isolated back surface*

Symbol	Test Conditions	Maximum Ratings	
FRMS	$T_{VJ} = T_{VJM}$ $T_{case} = 100$ °C; 180° sine	30 2 x 11	A A
FSM	$T_{VJ} = 45$ °C; $t = 10 \text{ ms}$ (50 Hz), sine $t = 8.3 \text{ ms}$ (60 Hz), sine	100 105	A A
	$T_{VJ} = 150^{\circ}\text{C}$; $t = 10 \text{ ms}$ (50 Hz), sine $t = 8.3 \text{ ms}$ (60 Hz), sine	85 90	A A
l²t	$T_{VJ} = 45^{\circ}\text{C}$ $t = 10 \text{ ms}$ (50 Hz), sine $t = 8.3 \text{ ms}$ (60 Hz), sine	50 45	A ² s A ² s
	$T_{VJ} = 150$ °C; $t = 10$ ms (50 Hz), sine $t = 8.3$ ms (60 Hz), sine	35 30	A²s A²s
T _{VJ} T _{VJM} T _{stg}		-40+150 150 -55+150	°C °C °C
T _L	1.6 mm (0.063 in) from case for 10 s	260	°C
V _{ISOL}	50/60 Hz RMS; I _{ISOL} ≤ 1 mA	2500	V~
F _c	Mounting Force	1165 / 2.515	N/lb
Weight		2	q

Symbol	Test Conditions	Characteristic Values		
I _R ^①	$V_{R} = V_{RRM;} T_{VJ} = 25^{\circ}C$	≤	10	μΑ
	$T_{VJ} = 150^{\circ}C$	≤	0.7	mA
V _F ^②	I _F = 10 A; T _{VJ} = 25°C	≤	1.22	V
	T _{vJ} = 125°C	≤	1.26	V
V_{T0}	For power-loss calculations only		0.8	V
r _T	$T_{VJ} = T_{VJM}$		41	$m\Omega$
R _{thJC}	DC current		1.8	K/W
R _{thCK}	DC current (with heatsink compound)	typ.	0.6	K/W
а	Maximum allowable acceleration		100	m/s ²

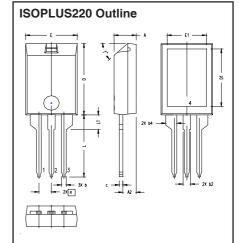
Notes: Data given for T $_{VJ}$ = 25°C and per diode unless otherwise specified \oplus Pulse test: pulse Width = 5 ms, Duty Cycle < 2.0 %

②Pulse test: pulse Width = 300 μs, Duty Cycle < 2.0 %

IXYS reserves the right to change limits, test conditions and dimensions.

Features

- · Silicon chip on Direct-Copper-Bond substrate
 - High power dissipation
 - Isolated mounting surface
 - 2500V electrical isolation
- · For single and three phase bridge configuration
- Low cathode to tab capacitance (<15pF)
- · Planar passivated chips
- Epoxy meets UL 94V-0



MILL IMPTEDS

MY2	INCUE2		MILLIME LEK?	
21M	MIN	MAX	MIN	MAX
Α	.157	.197	4.00	5.00
A2	.098	.118	2.50	3.00
b	.035	.051	0.90	1.30
b2	.049	.065	1.25	1.65
b4	.093	.100	2.35	2.55
С	.028	.039	0.70	1.00
D	.591	.630	15.00	16.00
D1	.472	.512	12.00	13.00
E	.394	.433	10.00	11.00
E1	.295	.335	7.50	8.50
е	.100 BASIC		2.55 BASIC	
L	.512	.571	13.00	14.50
L1	.118	.138	3.00	3.50
T°			42.5°	47.5°
NOTE				

INCHES

It:

Bottom heatsink (Pin 4) is electrically isolated from Pin 1, 2, or 3.

This drawing will meet dimensional requirement of JEDEC SS Product Outline 10–273 except D and D1 dimension.

DS98820(07/03)